

**REMARKS**

This Amendment is filed in response to the final Office Action dated March 16, 2009, and the Advisory Action dated June 24, 2009, and is respectfully submitted to be fully responsive to the rejections raised therein. Accordingly, favorable reconsideration on the merits and allowance are respectfully requested.

In the present Amendment, claims 1-11 have been canceled without prejudice.

Claim 12 has been rewritten in independent form to incorporate subject matter of canceled claim 1.

Claims 13-21 have been newly added and all depend, directly or indirectly, from independent claim 12. Claims 13-21 incorporate subject matters of canceled claims 2-11.

No new matter has been added. Entry of the Amendment is respectfully submitted to be proper. Upon entry of the Amendment, claims 12-21 will be all the claims pending in the application. Claims 12-21 are directed to a gallium nitride-based compound semiconductor light-emitting device comprising a transparent positive electrode.

**I. Claim Rejection under 35 U.S.C. §103**

Claims 1-3 and 5-12 were rejected under 35 U.S.C. §103 (a) as being unpatentable over Uemura (US 6,331,450 B1).

Applicants traverse and respectfully submit that claims 1-3 and 5-11 have been canceled and therefore the rejection of these are moot.

With respect to claim 12, Applicants request reconsideration and withdrawal of the rejection in view of the following remarks.

Applicants submit that claim 12 and newly added claims 13-21 are not rendered obvious over Uemura.

The present claims 12-21 are directed to a gallium nitride-based compound semiconductor light-emitting device.

Uemura fails to disclose or teach a gallium nitride-based compound semiconductor light-emitting device comprising a transparent positive electrode having a bonding pad layer on the current diffusing layer, and that the claimed thickness range of the contact metal layer is from 0.1 to 7.5 nm, as recited in present independent claim 12.

Specifically, Uemura discloses in Fig. 1 and Fig. 4A two separate and independent embodiments. There is no teaching or suggestion within Uemura for modifying and combining the disparate embodiments disclosed in Fig. 1 (flip-chip-type device - first embodiment) and Fig. 4 (wire-bonding-type device - third embodiment), to form a bonding pad layer 320 of Fig. 4A on the current diffusing layer 112 of Fig. 1.

Uemura also does not disclose or teach the claimed thickness range of the contact metal layer, as recited in present claim 12.

In view of the above, it is respectfully submitted that the present claims 12-21 are patentable over Uemura, and consideration and allowance is respectfully requested.

## **II. Conclusion**

In view of the above, reconsideration and allowance of this application are now believed to be in order, and such actions are hereby solicited. If any points remain in issue which the

AMENDMENT UNDER 37 C.F.R. § 1.114(c)  
U.S. Application No.: 10/593,288

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Examiner feels may be best resolved through a personal or telephone interview, the Examiner is kindly requested to contact the undersigned at the telephone number listed below.

The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

Respectfully submitted,



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CUSTOMER NUMBER

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